



ICF-624-S-O



PLCC-068-T-N

(2,54 mm) .100" (ICF) (1,27 mm) .050" (PLCC)

ICF, PLCC SERIES

SMT DIP & CHIP CARRIER SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?ICF or www.samtec.com?PLCC

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

BeCu

Plating:

Sn or Au over
50µ" (1,27 µm) Ni

Operating Temp Range:

-55°C to +125°C

Contact Resistance:

10 mΩ

Insertion Depth (ICF):

(2,54 mm) .100" to
(3,81 mm) .150"

Insertion

Force/Contact (ICF):

5 oz (1,39 N) average

Withdrawal

Force/Contact (ICF):

4 oz (1,11 N) average

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity (ICF):

.006" (0,15 mm) max

Lead Coplanarity (PLCC):

Less than 52 leads=

.006" (0,15 mm) max;

52 leads and more=

.008" (0,20 mm) max

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

ICF

ROW SPACING & NO. OF CONTACTS

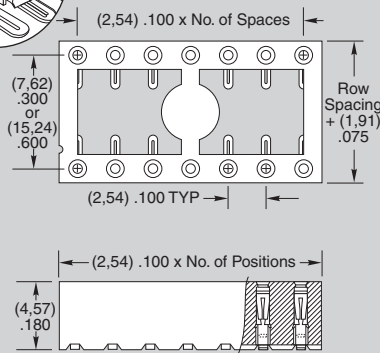
PLATING OPTION

TAIL OPTION

OTHER OPTION



Specify from chart below



"-XXX"	Row Space	No. of Contacts
-308	.300 (7,62)	08
-314		14
-316		16
-318		18
-320		20
-324	.600 (15,24)	24
-328		28
-624		24
-628		28
-632		32
-640		40

-S
=30µ"
(0,76 µm)
Gold on contact,
Matte Tin on tail

-T
= Matte Tin

-I
=Tails In

-O
=Tails Out

-TR
=Tape & Reel Packaging

PLCC

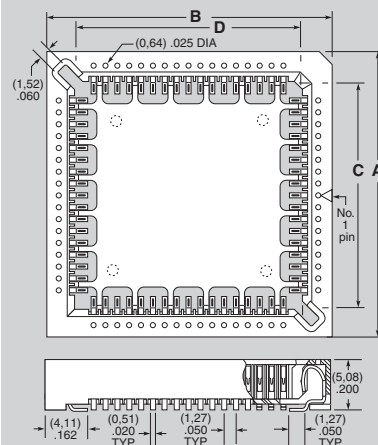
NO. OF CONTACTS

PLATING OPTION

ALIGNMENT PIN OPTION

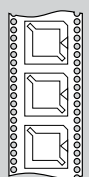
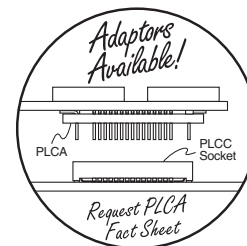
PACKAGE OPTION

-020, -032, -044, -068



*32 position has
.040" (1,00 mm) DIA x
.030" (0,76 mm) high
standoffs in corners.

NO. OF PINS	A	B	C	D
-020	.600 (15,24)	.600 (15,24)	.370 (9,40)	.370 (9,40)
-032	.700 (17,78)	.800 (20,32)	.470 (11,94)	.570 (14,48)
-044	.900 (22,86)	.900 (22,86)	.670 (17,02)	.670 (17,02)
-068	1.200 (30,48)	1.200 (30,48)	.970 (24,64)	.970 (24,64)



Leave package option blank for packaging in a tube.

Note:
Some sizes, styles and options are non-standard, non-returnable.